

	Hits	Search Text	DBs
3	73	(IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	77	(IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	42	(IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu)) and ((terminal or interconnect\$4) same ((integrated near5 circuit\$4) or IC)) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	39	(IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or cut\$4) same fuse same (resist or photoresist or photolithograph\$6 or lithograph\$7)) and (fuse same (metal\$4 or conduct\$4 or Cu)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
7	0	430/311.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM _ TDB
8	0	430/945.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM _ TDB

	Hits	Search Text	DBs
9	0	430/313.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	1	"430"/\$.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US-PPGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
11	12	257/529.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	3	257/762.ccls. and (IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
13	77	(IC or (integrated near5 circuit\$4)) and ((open\$4 or etch\$4 or remov\$4 or blow\$4 or ablat\$4 or (delet\$4 near9 laser)) same fuse) and (fuse same (metal\$4 or conduct\$4 or Cu or copper)) and (terminal or interconnect\$4) and (barrier or (diffus\$4 near5 barrier)) and (etch\$4 same (dry or wet)) and ((resist or photoresist) same (expos\$4 or illuminat\$4 or irradiat\$4)) and develop\$4 and pattern\$4	US-PPGUB; USPAT; EPO; JPO; DERWENT; IBM_TDB